TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

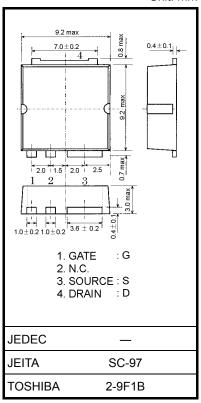
2SK3499

Switching Regulator and DC-DC Converter Applications Motor Drive Applications

- Low drain-source ON resistance: $RDS(ON) = 0.4 \Omega$ (typ.)
- High forward transfer admittance: $|\,Y_{\rm fs}\,|$ = 8.0 S (typ.)
- Low leakage current: I_{DSS} = 100 μA (max) (V_{DS} = 400 V)
- Enhancement model: V_{th} = 2.0 to 4.0 V (V_{DS} = 10 V, I_D = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	400	V	
Drain-gate voltage (R_{GS} = 20 k Ω)		V _{DGR}	400	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	۱ _D	10	А	
	Pulse (Note 1)	I _{DP}	40	A	
Drain power dissipation	n (Tc = 25°C)	PD	80	W	
Single pulse avalanche energy (Note 2)		E _{AS}	360	mJ	
Avalanche current		I _{AR}	10	А	
Repetitive avalanche energy (Note 3)		E _{AR}	8	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55 to150	°C	



Weight: 0.74 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.56	°C/W

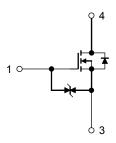
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD} = 90 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$ (initial), L = 5.85 mH, R_G = 25 Ω , I_{AR} = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Circuit Configuration



Unit: mm

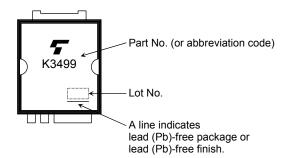
Electrical Characteristics (Ta = 25°C)

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS}=\pm 25~V,~V_{DS}=0~V$			±10	μA
Drain-source breakdown voltage		V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30	_		V
Drain cut-OFF current		I _{DSS}	$V_{DS} = 400 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			100	μA
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	400			V
Gate threshold v	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0		4.0	V
Drain-source ON	resistance	R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5.0 \text{ A}$		4.0	0.55	Ω
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5.0 \text{ A}$	4.0	0.8	_	S
Input capacitance		C _{iss}		_	1340	_	pF
Reverse transfer capacitance		C _{rss}	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		160		
Output capacitance		C _{oss}			490	_	
Switching time	Rise time	tr	$V_{GS}^{10 \text{ V}} \downarrow_{D} = 5 \text{ A} \\ 0 \text{ V} \downarrow_{O} \downarrow_{O} \downarrow_{O} \downarrow_{O} \\ R_{L} = 40 \Omega \\ V_{DD} \simeq 200 \text{ V} \\ Duty \le 1\%, t_{W} = 10 \mu \text{ s}$	_	22	_	
	Turn-ON time	t _{on}		_	60	_	
	Fall time	t _f		_	32	_	ns
	Turn-OFF time	t _{off}		_	140	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	34	_	nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 320 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	_	18	—	
Gate-drain ("miller") charge		Q _{gd}			16		

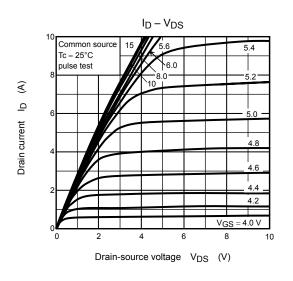
Source-Drain Ratings and Characteristics (Ta = 25°C)

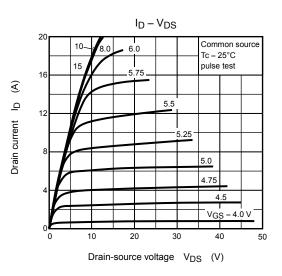
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	10	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	40	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 10 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V},$	_	350	_	μS
Reverse recovery charge	Q _{rr}	dl _{DR} /dt = 100 A/μs	_	3.6	_	μC

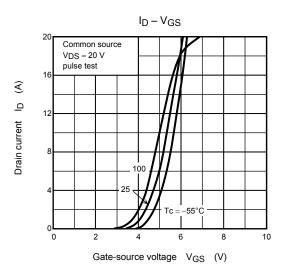
Marking

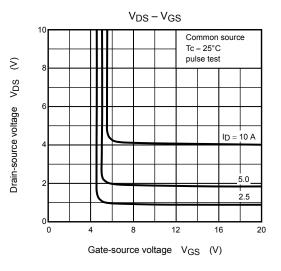


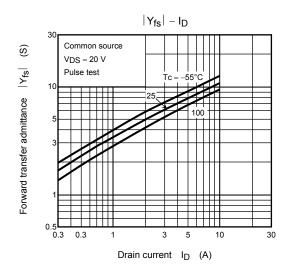
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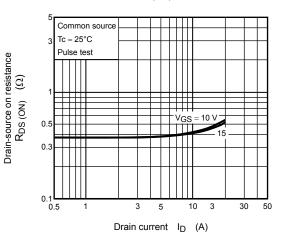




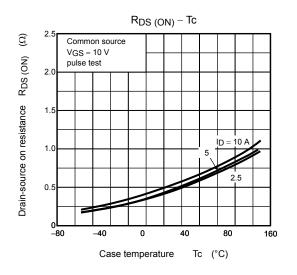


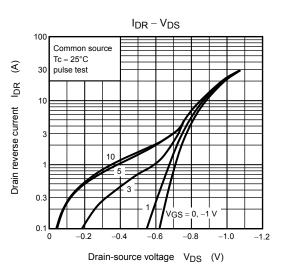


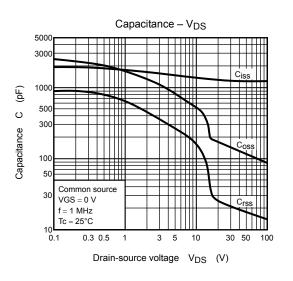
R_{DS} (ON) - I_D

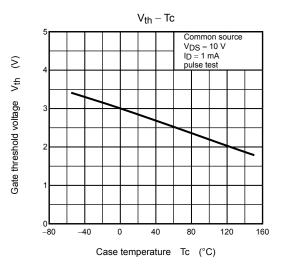


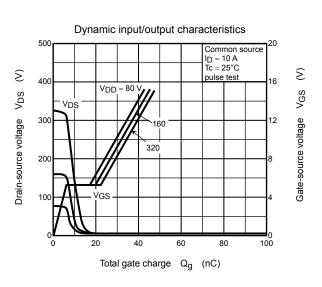
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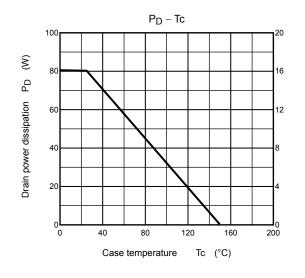


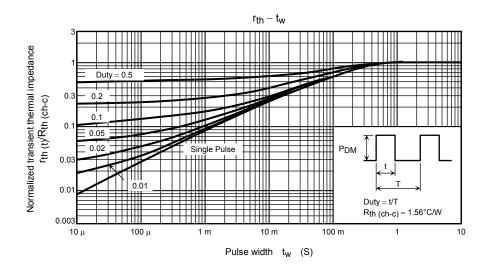




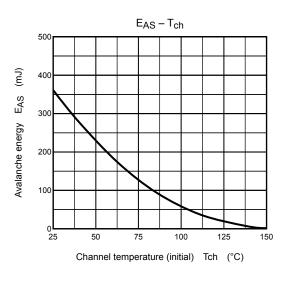


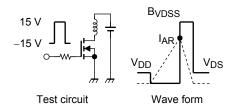


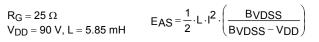




Safe operating area 100 (pulsed) * 50 In ma 30 00 ID ma (continuous) 10 E Drain current I_D DC operation 0.5 0.3 0.1 Single nonrepetitive pulse 0.05 $Tc = 25^{\circ}C$ V_{DSS} ma 0.03 Curves must be derated linearly with increase in temperature. 0.01 10 100 1000 1 Drain-source voltage V_{DS} (V)







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